

Data Sheet January 2000 File Number 1885.5

## 8A, 200V Ultrafast Dual Diodes

The MUR1620CT and RURP820CC are ultrafast dual diodes with soft recovery characteristics ( $t_{rr}$  < 25ns). They have low forward voltage drop and are silicon nitride passivated ionimplanted epitaxial planar construction.

These devices are intended for use as freewheeling/ clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and ultrafast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

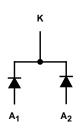
Formerly developmental type TA09224.

## **Ordering Information**

PART NUMBER	PACKAGE	BRAND
MUR1620CT	TO-220AB	MUR1620C
RURP820CC	TO-220AB	RURP820C

NOTE: When ordering, use the entire part number.

## Symbol



### **Features**

•	Ultrafast with Soft Recovery	S
•	Operating Temperature	С
•	Reverse Voltage	V

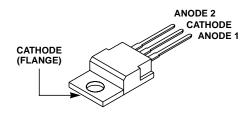
- Avalanche Energy Rated
- Planar Construction

## **Applications**

- · Switching Power Supplies
- · Power Switching Circuits
- · General Purpose

## **Packaging**

**JEDEC TO-220AB** 



MUD1620CT

### Absolute Maximum Ratings (Per Leg) T<sub>C</sub> = 25°C, Unless Otherwise Specified

	RURP820CC	UNITS
Peak Repetitive Reverse VoltageV <sub>RRM</sub>	200	V
Working Peak Reverse Voltage	200	V
DC Blocking VoltageV <sub>R</sub>	200	V
Average Rectified Forward Current $I_{F(AV)}$ ( $T_C = 157^{\circ}C$ )	8	Α
Repetitive Peak Surge Current I <sub>FRM</sub> (Square Wave, 20kHz)	16	Α
Nonrepetitive Peak Surge Current	100	Α
Maximum Power Dissipation	50	W
Avalanche Energy (See Figures 10 and 11)	20	mJ
Operating and Storage Temperature	-65 to 175	oC

## MUR1620CT, RURP820CC

**Electrical Specifications** (Per Leg)  $T_C = 25^{\circ}C$ , Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
V <sub>F</sub>	I <sub>F</sub> = 8A	-	-	0.975	V
	$I_F = 8A, T_C = 150^{\circ}C$	-	-	0.895	V
I <sub>R</sub>	V <sub>R</sub> = 200V	-	-	100	μΑ
	V <sub>R</sub> = 200V, T <sub>C</sub> = 150°C	-	-	500	μΑ
t <sub>rr</sub>	$I_F = 1A$ , $dI_F/dt = 200A/\mu s$	-	-	25	ns
	$I_F = 8A$ , $dI_F/dt = 200A/\mu s$	-	-	30	ns
t <sub>a</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	13	-	ns
t <sub>b</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	5	-	ns
Q <sub>RR</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	25	-	nC
СЈ	V <sub>R</sub> = 10V, I <sub>F</sub> = 0A	-	60	-	pF
R <sub>θJC</sub>		-	-	3	°C/W

#### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

 $I_R$  = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (See Figure 9), summation of  $t_a + t_b$ .

 $t_a$  = Time to reach peak reverse current (See Figure 9).

 $t_b$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

 $Q_{RR}$  = Reverse recovery charge.

 $C_J$  = Junction Capacitance.

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = Pulse width.

D = Duty cycle.

## **Typical Performance Curves**

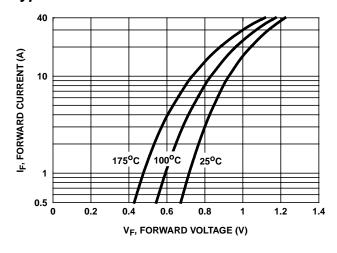


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

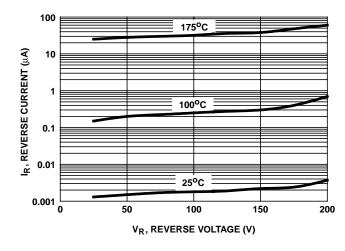


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

# Typical Performance Curves (Continued)

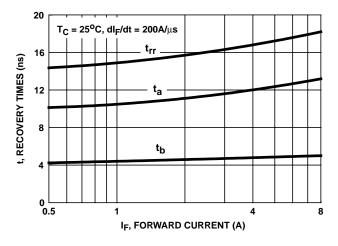


FIGURE 3.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

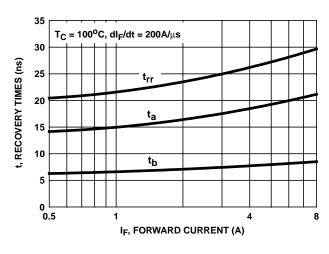


FIGURE 4.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

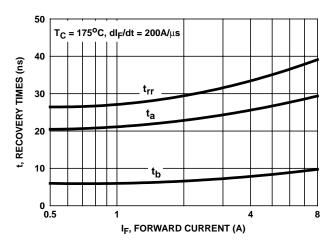


FIGURE 5. t<sub>rr</sub>, t<sub>a</sub> AND t<sub>b</sub> CURVES vs FORWARD CURRENT

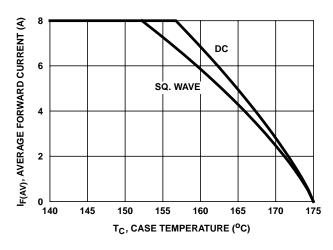


FIGURE 6. CURRENT DERATING CURVE

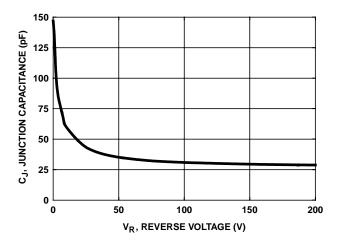


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

### Test Circuits and Waveforms

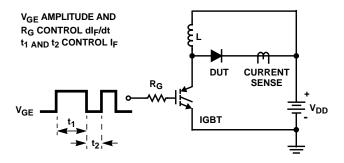


FIGURE 8. t<sub>rr</sub> TEST CIRCUIT

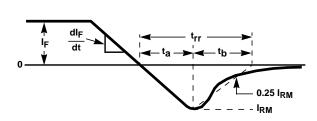


FIGURE 9. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

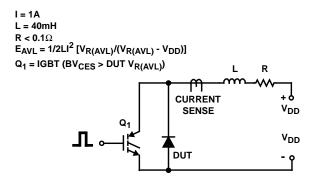


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

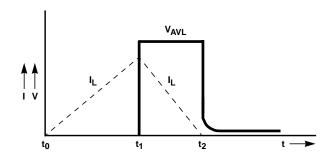


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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